

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 05/06/2022

Details for "LT1014DIN"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LT1014DIN	NIPDAU	Level-NC-NC-NC	TI AGUASCALIENTES	N 14	6.35x19.3x4.57	1624.4

*Total Device Mass
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.099656	99.998997	999990	0.006135	61
Precious Metals	Silver	7440-22-4	0.000001	0.001003	10	0	0
Sub-Total			0.099657	100	1000000	0.006135	61
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.393487	78.999982	790000	0.085783	858
Thermoplastics	Epoxy	85954-11-6	0.370421	21.000018	210000	0.022803	228
Sub-Total			1.763908	100	1000000	0.108586	1086
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	398.315522	97.05	970500	24.520302	245203
Copper and Its Alloys	Iron	7439-89-6	10.670998	2.6	26000	0.656907	6569
Copper and Its Alloys	Phosphorus	7723-14-0	0.615635	0.15	1500	0.037898	379
Zinc and Its Alloys	Zinc	7440-66-6	0.820846	0.2	2000	0.050531	505
Sub-Total			410.423001	100	1000000	25.265638	252656
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.357362	95.119972	951200	0.083559	836
Precious Metals	Gold	7440-57-5	0.011131	0.780028	7800	0.000685	7
Precious Metals	Palladium	7440-05-3	0.058507	4.1	41000	0.003602	36
Sub-Total			1.427	100	1000000	0.087846	878
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	1059.787109	88	880000	65.24049	652405
Other Plastics and Rubber	Carbon Black	1333-86-4	3.612911	0.3	3000	0.222411	2224
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	6.623669	0.55	5500	0.407753	4078
Thermoplastics	Epoxy	85954-11-6	134.279844	11.15	111500	8.266267	82663
Sub-Total			1204.303533	100	1000000	74.13692	741369
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	6.414465	100	1000000	0.394874	3949
Sub-Total			6.414465	100	1000000	0.394874	3949
Total			1624.431564			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products
TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.